

Title (en)

WIRING BOARD, ELECTRONIC DEVICE AND ELECTRONIC MODULE

Title (de)

LEITERPLATTE, ELEKTRONISCHE VORRICHTUNG UND ELEKTRONISCHES MODUL

Title (fr)

CARTE DE CÂBLAGE, DISPOSITIF ÉLECTRONIQUE ET MODULE ÉLECTRONIQUE

Publication

EP 3846202 B1 20230927 (EN)

Application

EP 19856280 A 20190828

Priority

- JP 2018160533 A 20180829
- JP 2018204113 A 20181030
- JP 2019033655 W 20190828

Abstract (en)

[origin: US2021176855A1] A wiring substrate includes: an insulating substrate including a base portion comprising a through hole having a first opening and a second opening, and a frame portion located on the base portion; and a heat dissipator disposed on a side of the base portion that is opposite to the frame portion so as to block the second opening, wherein an inner surface of the through hole faces a side surface of the heat dissipator with a clearance being provided between the inner surface of the through hole and the side surface of the heat dissipator.

IPC 8 full level

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CPC (source: EP US)

H01L 23/13 (2013.01 - EP); **H01L 23/36** (2013.01 - EP); **H01L 23/3677** (2013.01 - EP); **H01L 31/02** (2013.01 - EP); **H01L 33/62** (2013.01 - EP); **H05K 1/0209** (2013.01 - US); **H05K 1/021** (2013.01 - EP); **H05K 1/184** (2013.01 - US); **H05K 3/103** (2013.01 - US); **H05K 1/184** (2013.01 - EP); **H05K 2203/049** (2013.01 - EP)

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DOCDB simple family (publication)

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